## SHARP <br> THE IDEAS COMPANY



## Sharp Profile

〇Net Sales in FY'95
Y 1,281,752 million
©Capital Stock as of Mar.31, ‘96 Y 198,325 million
OCapital Investment in FY '95 Y 138,358 million
OR \& D Investment in FY ‘95
Y 115,330 million

Non-consolidated base
FY '95: Apr. '95 to Mar. '96
vs. '95
107.0
108.0
(5.4)

ONet Income
: 51,000
(2.9)
: 1,770,000
96,000 Special Items
( ): Proportion to net sales

## '95 Financial Results

Consolidated ( Y M, \%)

|  | $\quad 95$ | vs.'94 | $\mathbf{\prime 9 4}$ |
| :--- | ---: | ---: | ---: |
| Net Sales | $1,650,708$ | 102.0 | $1,617,620$ |
| Operating Income | 89,381 | 111.3 | $\mathbf{8 0 , 3 1 1}$ |
|  | $(5.4)$ |  | $(5.0)$ |
| Income before | $\mathbf{8 8 , 4 9 9}$ | 114.6 | 77,223 |
| Special Items | $(5.4)$ |  | $(4.8)$ |
| Net Income | 46,319 | 104.1 | 44,508 |
|  | $(2.8)$ |  | $(2.8)$ |

( ): Proportion to net sales

## ‘95 Financial Results

Non-consolidated ( $\mathbf{Y} \mathrm{M}, \%$ )

|  | 95 | vs.'94 | 94 |
| :--- | ---: | ---: | ---: |
| Net Sales | $\mathbf{1 , 2 8 1 , 7 5 2}$ | $\mathbf{1 0 1 . 6}$ | $\mathbf{1 , 2 6 1 , 5 6 2}$ |
| Operating Income | $\mathbf{5 7 , 9 1 9}$ | 103.3 | $\mathbf{5 6 , 0 6 2}$ |
|  | $(\mathbf{4 . 5 )}$ |  | $(4.4)$ |
| Income before | $\mathbf{7 0 , 5 3 0}$ | 105.2 | $\mathbf{6 7 , 0 7 3}$ |
| Special Items | $(5.5)$ |  | $(5.3)$ |
| Net Income | 39,372 | 113.7 | $\mathbf{3 4 , 6 3 1}$ |
|  | $(3.1)$ |  | $(2.7)$ |

( ): Proportion to net sales

# 11 Manufacturing Groups 



TV \& Video Systems Group
S. Shiotsu, Senior Executive Director

H. Inoue, Senior Executive Director (Concurrent)




## Sharp Europe

OSubsidiaries in<br>OGermany<br>©Sweden<br>OUnited Kingdom<br>-Belgium<br>- Austria<br>OSwitzerland<br>OFrance<br>OItaly<br>OSpain<br>ONetherlands<br>ODenmark

ODistributors in Greece
Portugal, Finland, Norway, Iceland, Russia, Butgaria, Romania, Ukraine, Slovenia, Belărus, Estonía, Lithuania, Rep. of Kazakhstan, Rep. of Georgia, Czech Republic, Slovak Republic, Hungary,
Latvia, Poland, Israel,

## Manufacturing in Europe

ЭUK: Copier systems, electronic typewriters, video recorders, microwave ovens.
FFrance: Telefax systems and copier systems
Spain: Colour TVs and telefax systems

## Development in Europe Sharp Laboratories of Europe Ltd.

Optoelectronic
OImaging technology
OInformation technology

- Liquid crystal

OStrategy \& planning
OAdministration

## SHARP



SEEG

## Sharp Electronic (Europe) GmbH Sales in Europe

## CED

## Consumer Electronics Division

©ViewCam
Ovideo printers
©colour TVs
Ovideo recorders
ЭLCD-projetors
Ocordless telephones
Omicrowave ovens

Эair conditioners
〇audio systems
Ostereo radio-recorders

- MiniDisc recorders
cassette-players


## ISD

## Information Systems Division

Ocopier systems
Oscanners
Olaser printers
Otelefax systems
Onotebooks
Qelectronic organizers

Ocalculators
Oelectronic typewriters
Ocash registers

## VPE

${ }^{2}$ LCD projectors for professional usage with data displays, video displays and multimedia applications
$\quad$ LCD-monitors
computer projection panels

## GSM

ЭGSM TQ-G400
Handy Telephone
ЭGSM accessories
©complete "Mobil Office" incl. Handy, ZR-5000 G and PCMCIA GSM Fax/Datacard

## MED

OLC-Displays
Oopto-electronic device
Ointegrated circuits
$\quad$ RF components
OSolar cells
-CCD's

## SHARP



## SHARP Microelectronics

 Support Network Europe


## Key Components for Powerful Systems

OFlat Panel Displays
OOptoelectronic Devices
OPower Devices
-LED/Laser Components
ORF Components
OIntegrated Circuits
OMechanical Devices and others
OSolar Cells/Modules

## Flat Panel Displays



Accelerating a Multimedia Future

## SHARP



## Flat Panel Displays

-Colour TFT-LCD Modules
-Colour STN-LCD Modules
-Passive Dot Matrix LCD Modules
OElectroluminescent Display Modules

## Colour TFT-LCD Modules

〇TFT for Monitor/FA/OA
-size: 6.4", 8.4", 10.4", 11.3", 12.1", 13.8", 15", 17.x"
-Resolution: VGA, SVGA, XGA, SXGA
-S2-technology for high aperture ratio
-Wide viewing Angle
-High brightness, high transmissivity
-Long life CCFT 25Khrs (typ.)
-CPP types available
-High light and het durability

## Colour TFT-LCD Modules

OTFT for Automotive / AV
-Size: 3", 4", 5", 5.5", 5.7", 6.4", 7.2", 8.6"
-Interface: RGB-analog, PAL-composite, NTSC-composite
-Extended Temp. range $\left(-30^{\circ} \mathrm{C}\right.$ to $\left.+85^{\circ} \mathrm{C}\right)$ with integrated backlight -Wide Viewing angle ( $120^{\circ}$ )
-Display rotation function
-16:9 Aspect ratio

## Colour STN-LCD Modules

ЭSize: 5.5", 8.0", 8.4", 9.4", 10.4", 11.3", 12.1", 13.8", 15", 17.7"
ЭResolution: QVGA, VGA, SVGA, XGA
OHigh brightness types > $150 \mathrm{~cd} / \mathrm{m} 2$
OLong life CCFT 25 Khrs (typ.)
-Mech. compatible to TFT
-Sharp Addressing for improved picture quality

## Passive Dot Matrix LCD Modules

-Resolution: 16x1, 16x2, 20x2, 40x2, QVGA〇TN, STN with LED backlight
OStandard Interface

## Electroluminescent Display Modules

-320x240 to $1024 \times 768$
Ohigh brightness ( $200 \mathrm{~cd} / \mathrm{m} 2$ )
Oupto 16 greyscale
OLCD interface
Ohigh contrast moduls (require to circular polarizer)

## Optoelectronic Components



Advanced Optoelectronics Technology to Meet Tomorrows`s Needs Today

## Optoelectronic Components

## -OPIC*

*OPIC (Optical IC) is trademark of the SHARP Corporation
OInfrared Ermitting Diodes and Photodiodes
-Photocouplers
PPhotointerrupters
OIR detecting units for remote control
-Fiber Optics
Optical System Device

## Main Features of

## Optoelectronic Components

## OInfrared Ermitting Diodes and Photodiodes

-Models with beam angle for combination with various
Photodetectors
-Double-end models for surface mounting
-Can-packaged models that provide high-reliability
-Models with SHARP's OPIC technology to improve
function of Photodetector
-Blue Sensitive Photodiodes
-Position Sensitive Detectors

## Main Features of Optoelectronic Components

## PPhotocouplers

-High isolation models made using double transfer mold technology <Viso-5.000V>
-Compact SMD type for automatic molding
-Half pitch type
-Wide product line-up approved safety standard UL,TÜV,VDE etc
-Models with variety of outputs which meet the needs of various applications
$\gg$ OPIC output for high speed/high functional equipment
$\gg$ Phototriac/thyristor output for triggering of triac/thyristor for power supplies

## Main Features of Optoelectronic Components

## PPhotointerrupters

-Reflective and transmissive types
-Models with a variety of shapes and outputs
-Ultra-compact models made using a two-layer resin
-High functional models which use our OPIC technology
-Ultra-compact models with leadless chips for high-density mounting by using MID technology
-High-resolution models for high-precision detection
-Suitable for detecting high-speed rotation

## Main Features of Optoelectronic Components

## OIR Detecting Units for Remote Control

-Compact, thin and ultra compact SMD models with our OPIC technology
-IR Units with mesh for improved EMI resitance
-Compatible with various "BPF frequencies"

## Main Features of Optoelectronic Components

## OFiber Optic

-High-speed signal transmission ( $25 \mathrm{MB} / \mathrm{s}$ for OA equipment, $8 \mathrm{MB} / \mathrm{s}$ for AV equipment
-Models with optical mini-jack (for AV equipment) to accommodate optical/analogue/digital signals

## OOptical Systems Devices

-High performance due to Position Sensitive Device
-Distance Measuring Sensors
-Optical Pointing Device

## Power Devices

〇LCD Backlight Inverters
OLow-Power-Loss Voltage Regulators
-Chopper Regulators
PPrimary Regulators
OSolid State Relais
PPhototriac/Photothyristor

## Main Features of Power Devices

## DLow-Power-Loss Voltage Regulator

-Low power loss that makes it easier to design smaller, lighter, energy-saving equipment. Voltage diffrence between input and output: 0.5 V MAX
-Multi functional models. (ON/OFF control function, minute adjustable output, variable output, low dissipation current at OFF-state, reset signal generation function etc.)
-Various build-in protection circuits (Overcurrent, overheat, reverse voltage etc.)
-4-pin compact, full mold package models (TO-220)
Surface mount package models (SC-63)

## Main Features of Power Devices

## -Chopper Regulators

-Only a few externally attached components required.
-Various build-in functions (ON/OFF control; overheat; overcurrent protection)
-Compact surface-mount package

## OPrimary Regulator

-Build-in power MOS-FET control IC
-Low-Power-loss due to build in overcurrent protecion circuit

## Main Features of Power Devices

## OSolid State Relais

-Models with a zero-cross circuit to minimize the generation of noise
-Models with snubber circuit to control surge current
-A variety of package styles (SIP,DIP)

## -Phototriac/Photothyristor

-Various Packages available
-Output Voltages up to 800 V

## SHARP

Solar Cell/Modules
-Space Use
©Terrestrial Use OConsumer Use


## LED/Laser <br> Components

OThrough hole LEDs
-SMD LEDs
OLED for Bar Graphic Displays
OLED Units
-Laser Diodes

## Main Features of

Optoelectronic Components

## OThrough hole LEDs

-Wide variety of packages
-High brightness materials (AIGaInp, TS AIGaAS)
-Dichromatic LEDs

## OSMD LEDs

-Chipled types
-MID types (molded interconnected device)
-Dichromatic and RGB SMD LEDs

## LED for bar graph displays

-seven segment displays
-Backlightning modules
-LED arrays for scanners

## Main Features of Optoelectronic Components

## OLED Units

-Outdoor Dot Matrix LED units
-Indoor Dot Matrix LED units
-Monochrome and Dichromatic and RGB
-varies sizes and dot pitches
-Clusters
OLaserdiodes
-Hologram Lasers
-Laserdiodes
-visible and infrared

## RF units

- LNB-specified for digital broadcasting

ƏFront End units for digital DBS broadcasting
FFront End units for digital CATV broadcasting
Tuner for analog DBS reception
©RF modulator
-RF transend units for cordless phones,
DECT, CT1, CT1+


## Integrated Circuits

OMicro Processors

- Memories
- ASCICs

OOther ICs

2-bit, 8-bit Single Chip
Microcomputers
-Single Chip Systems (32-bit CPU CORE)

## SHARP <br> 

Memories
-DRAM's
-SRAM's
-Pseudo SRAM's

- Mask ROM's
-Flash Memories
©EPROM
-FIFO's
-IC Memory Cards JEDEC PCMCIA


## SHARP


-CPU Core ASSP's
-Cell-based ASIC's
OGate Arrays with
Built-in Core CPU
ЭARM based ASSP's
$\xlongequal{\partial}$ CCD Sensor Chips
OHall IC's
©HEMT

- MMIC's
- LCD Drivers

OBipolar IC's

## Mechanical Devices and Others

〇CCD Modules/Units
OHall Devices
OCD Pick-up Units/Mechanism
〇Magneto-Optical Disks
©MD Pick-up Units/Mechanism

- Magneto-optical Disk Drivers
- PCBs

